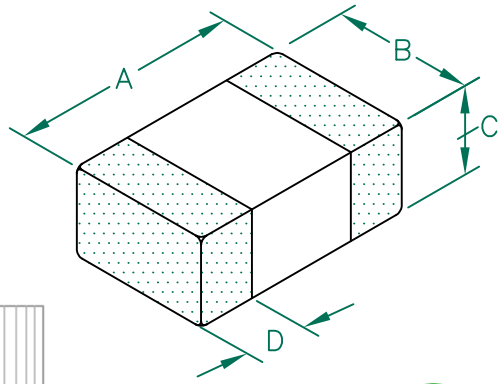
CPI0805F2R2R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

A	2.00 [.079]	± 0.20[.008]
B	1.25 [.049]	± 0.20[.008]
C	0.90 [.035]	± 0.10[.004]
D	0.50 [.020]	± 0.20[.008]

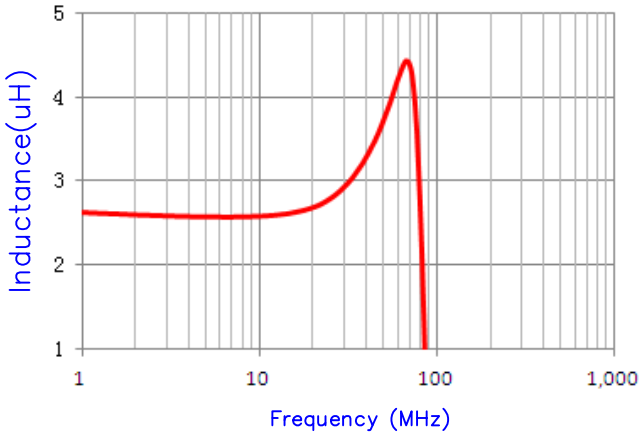


ELECTRICAL CHARACTERISTICS:

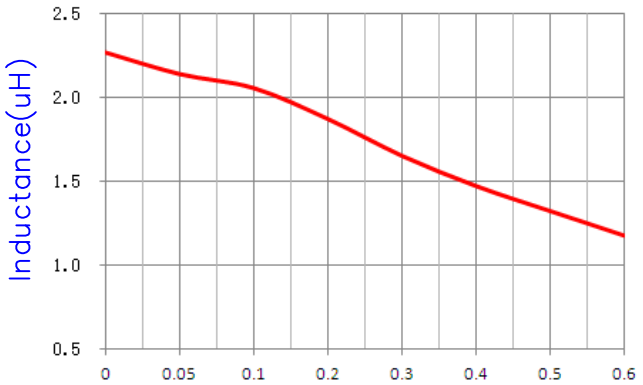
	L (μH) @ 1MHz ± 20%	DCR (Ω) ± 25%	I (Max)
Nom	2.2	0.25	
Min	1.8	0.1875	
Max	2.6	0.3125	600mA

NOTES: UNLESS OTHERWISE SPECIFIED
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
5. Operation Temperature TEMP: −55°C~+125°C. (INCLUDING SELF−HEATING)

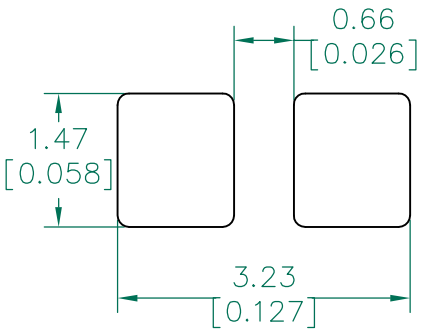
Ls vs Frequency



Ls vs DC BIAS Current

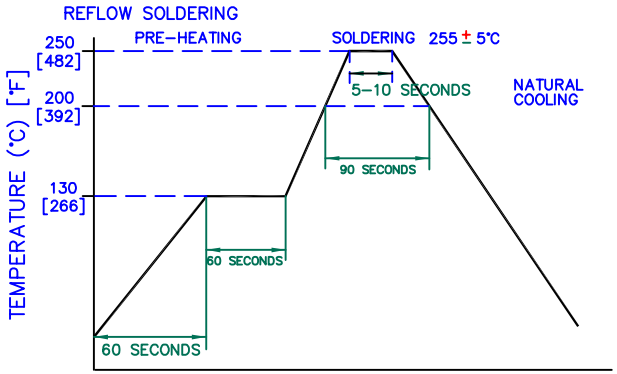


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering. add 0.763 [0.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS



RoHS 2002/95/EC

REV	DESCRIPTION	DATE	INT
C	CHANGE PLASTIC TAPE TO PAPER TAPE	04/17/14	QU
B	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU
A	ORIGINAL DRAFT	03/01/11	QU

DIMENSIONS ARE IN mm [INCHES].

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Laird

PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:
CPI0805F2R2R−10	C	CO−FIRE	QU

DATE:	SCALE:	SHEET:
03/01/11	NTS	1 of 1

CAD # CPI0805F2R2R−10−A TOOL # −